

BT151 Series

Description:

High current density due to singel mesa technology.
 BT151 series of silicon controlled rectifiers are specifically designed for medium power switching and phase control applications.

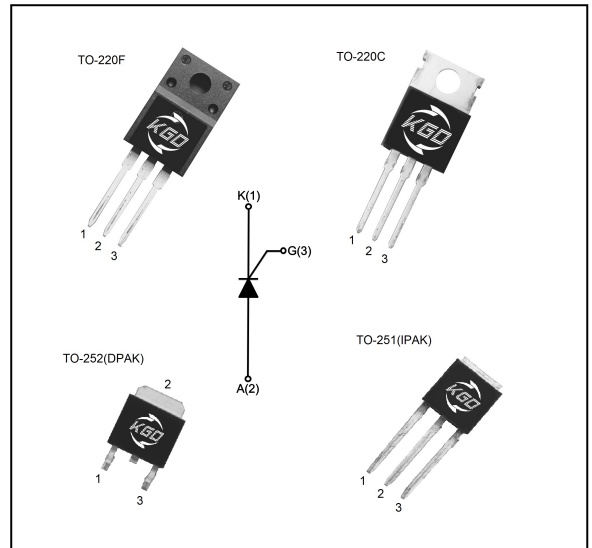
BT151 series are suitable for general purpose applications, a high gate sensitivity is required.

BT151F are full pack plastic package, they provides a 2000V RMS isolation voltage from all three terminals to external heatsink.

Features:

- Blocking voltage to 500/650/800V
- On-state RMS current to 12A
- Non-repetitive peak on-state current to 120A

Absolute Maximum Ratings



Symbol	Parameter	Conditions	Value	Unit	
V_{DRM}	Repetitive peak off-state voltage	BT151-500R	500	V	
		BT151-650R	$T_J=25^{\circ}C$		650
		BT151-800R			800
$I_{T(RMS)}$	RMS on-state current (all conduction angels)	IPAK/DPAK	$T_c=100^{\circ}C$	A	
		TO-220C	$T_c=109^{\circ}C$		12
		TO-220F	$T_c=69^{\circ}C$		
$I_{T(av)}$	Average on-state current (half sine wave)	IPAK/DPAK	$T_c=100^{\circ}C$	A	
		TO-220C	$T_c=109^{\circ}C$		7.5
		TO-220F	$T_c=69^{\circ}C$		
I_{TSM}	Non-repetitive surge peak On-state current (half sine cycle $T_J=25^{\circ}C$)	f= 50Hz	tp=10ms	120	A
		f= 60Hz	tp=8.3ms	132	
I^2t	I^2t Value for fusing		tp=10ms	72	A^2S
di_T/dt	Repetitive rate of rise of on-state current after triggering			50	$A/\mu s$
	$I_{TM}=20A$ $I_G=50mA$ dI_G/dt 50Ma/ms				

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I_{GM}	Peak gate current	tp=20 μ s, T _J =125°C	2	A
P_{GM}	Peak gate power		5	W
$P_{G(AV)}$	Average gate power dissipation		0.5	W
T _{STG}	Storage temperature		-40 150	°C
T _J	Junction temperature		-40 110	°C

● Electrical Characteristics

Symbol	Conditions	Value			Unit
		MIN	TYP	MAX	
I_{GT}	$V_D=12V, R_L=33\Omega$	/	3	15	mA
V_{GT}		/	0.6	1.5	V
V_{GD}	$V_D=V_{DRM}, R_L=3.3K\Omega, T_J=110^\circ C$	/	/	0.2	V
I_L	$I_G=1.2I_{GT}$	/	10	40	mA
I_H	$I_T=500mA$	/	8	30	mA
dv/dt	$V_{DM}=67\%V_{DRM}, \text{gate open}, T_J=125^\circ C$	200	400	/	V/ μ s

● Electrical Characteristics

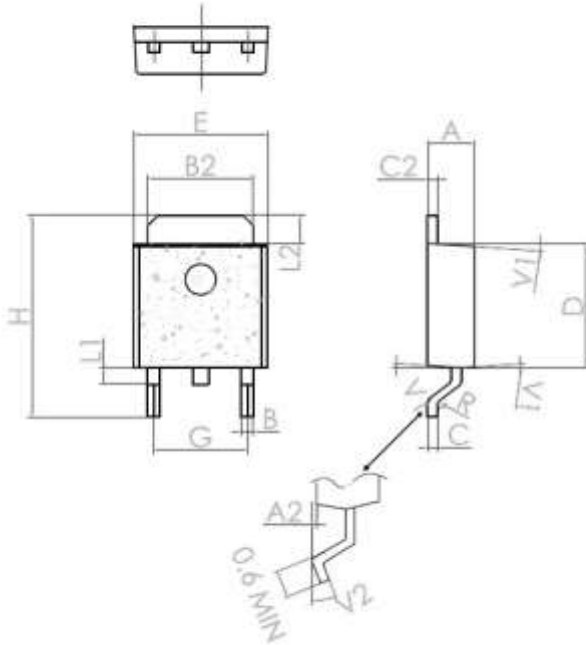
Symbol	Parameter	Numerical	Unit
V_{TM}	$I_T=23A, t_p=380\mu s$ T _J =25°C	1.7	V
I_{DRM}	$V_D=V_{DRM}, V_R=V_{RRM}$	T _J =25°C	10 μ A
I_{RRM}		T _J =125°C	0.5 mA

● Thermal Characteristics

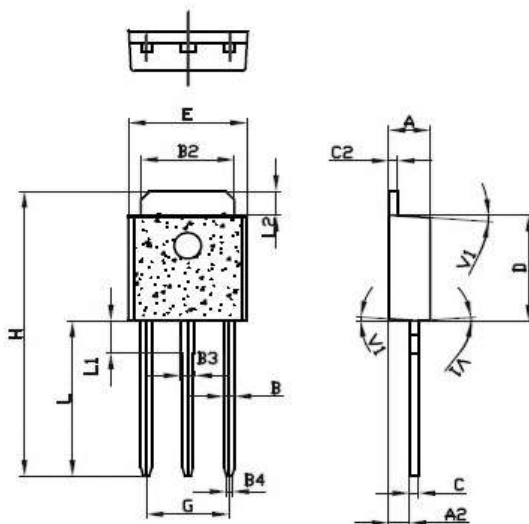
Symbol	Parameter	Numerical(MAX)	Unit
$R_{th(j-mb)}$	Thermal resistance from junction to mounting base	TO-220C	1.3
		IPAK/DPAK	2.0
$R_{th(j-hs)}$	Thermal resistance from junction to heatsink compound	TO-220F	4.5

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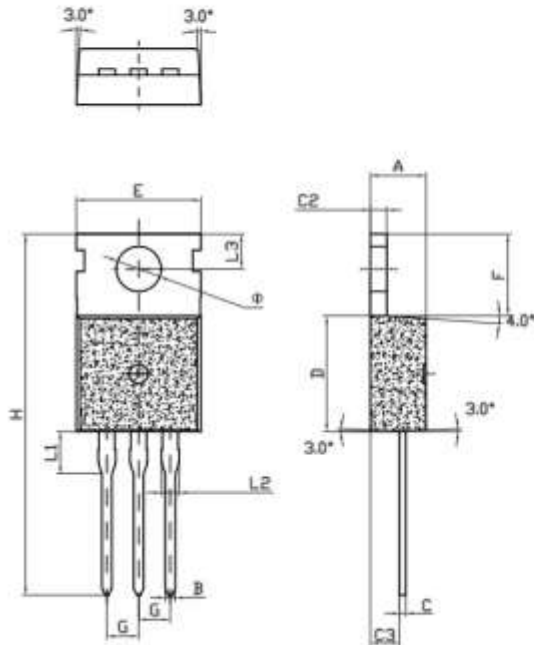
● Package Outline Dimensions

TO-252 / DPAK


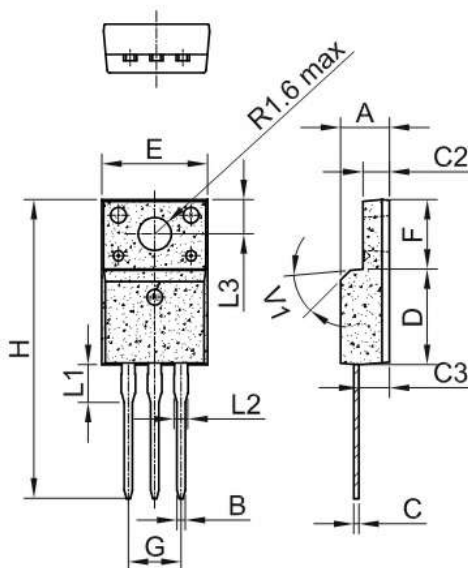
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.095
A2	0.03		0.23	0.001		0.009
B	0.55		0.65	0.021		0.026
B2	5.2		5.4	0.204		0.212
C	0.45		0.62	0.017		0.024
C2	0.48		0.62	0.019		0.024
D	6		6.2	0.236		0.244
E	6.4		6.6	0.251		0.259
G	4.40		4.60	0.173		0.181
H	9.35		10.1	0.368		0.397
L1		0.8			0.031	
L2	1.37		1.5	0.054		0.059
V1		4°			4°	
V2	0°		8°	0°		8°

TO-251(iPAK)


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.095
A2	0.9		1.1	0.035		0.043
B	0.55		0.65	0.021		0.026
B2	5.1		5.4	0.200		0.212
B3	0.76		0.85	0.030		0.033
B4		0.32			0.013	
C	0.45		0.62	0.017		0.024
C2	0.48		0.62	0.019		0.024
D	6		6.2	0.236		0.244
E	6.4		6.7	0.252		0.264
G	4.4		4.7	0.173		0.185
H	16.0		16.7	0.630		0.658
L	8.9		9.4	0.350		0.370
L1	1.8		1.9	0.071		0.075
L2	1.37		1.5	0.054		0.059
V1		4°			4°	

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TO-220C


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.6	0.173		1.181
B	0.7		0.9	0.027		0.035
C	0.45		0.6	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.2		2.6	0.086		0.102
D	8.9		9.9	0.350		0.390
E	9.9		10.3	0.390		0.406
F	6.3		6.9	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	11.0		11.7
L1		3.2			0.126	
L2	1.14		1.7	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

TO-220F


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.8	0.173		0.189
B	0.74	0.8	0.83	0.029	0.031	0.033
C	0.5		0.75	0.020		0.030
C2	2.4		2.7	0.094		0.106
C3	2.6		3.0	0.102		0.118
D	8.8		9.3	0.346		0.367
E	9.7		10.3	0.382		0.406
F	6.4		6.8	0.252		0.268
G	5.0		5.2	0.197		0.205
H	28.0		29.8	11.0		11.7
L1		3.63			0.143	
L2	1.14		1.7	0.044		0.067
L3		3.3			0.130	
V1		40°			40°	

FIG.1: Maximum power dissipation versus average on-state current(half cycle)

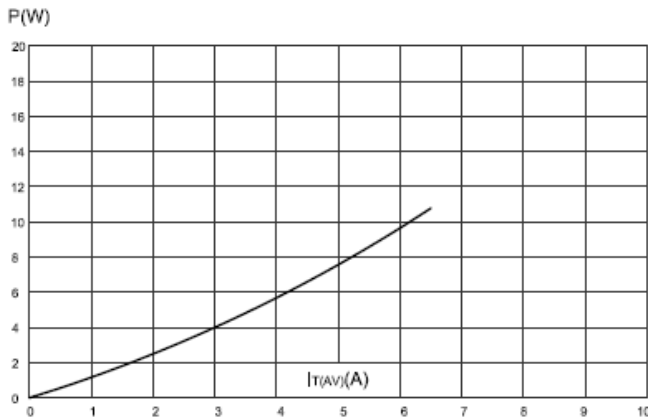


FIG.2: RMS on-state current versus case temperature(full cycle)

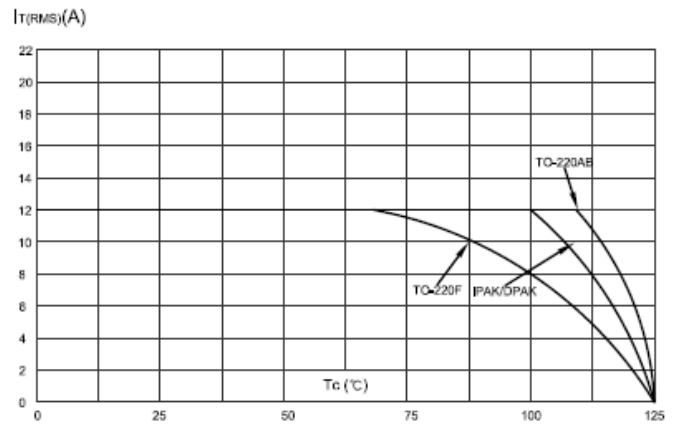


FIG.3: On-state characteristics (maximum values).

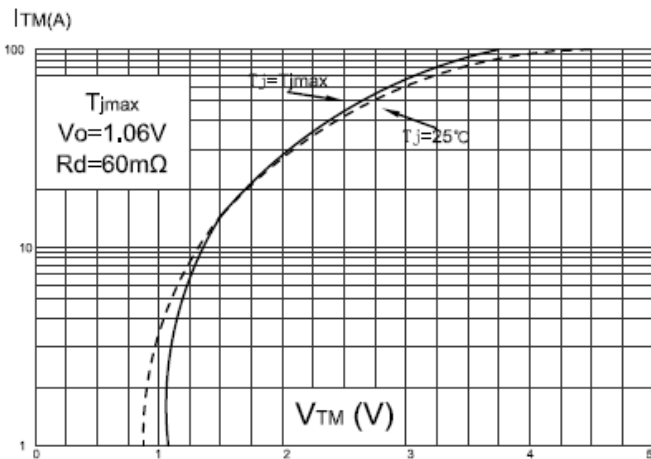


FIG.4: Surge peak on-state current versus number of cycles.

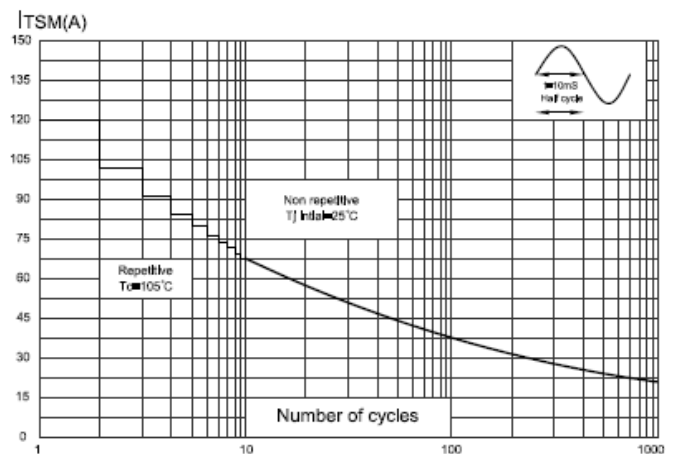


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t .

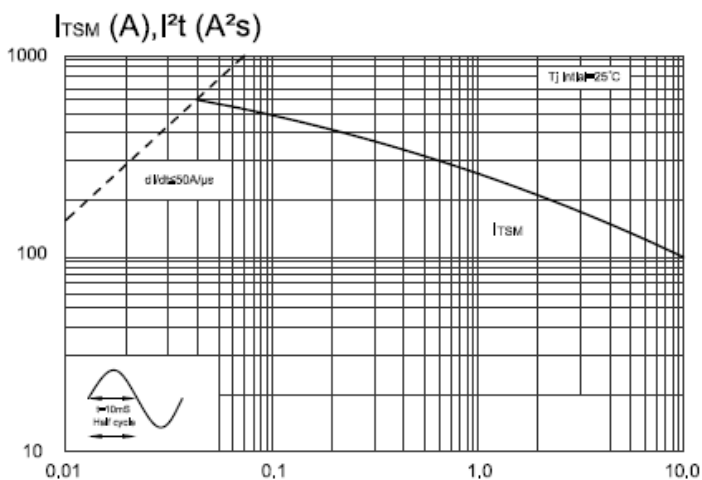


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)

